

HIGH CURRENT GLASS PASSIVATED SINGLE_PHASE
BRIDGE RECTIFIER

特 点

FEATURES

The plastic package has Underwriters Laboratory
flammability recognition 94V-0

外壳已经 UL 可燃性认证 94V_0

Integrally molded heatsink provide very low thermal
resistance for maximum heat dissipation

铝散热片，热阻抗低，散热量大

Universal 3_way terminals; snap_on, wire wrap
_around, or P.C. Board mounting

通用 3_路端子；搭锁，引线缠绕或 PC 板安装

Surge overload ratings to 400 Amperes

浪涌过载额定值达 400 安培

Glass passivated chip junctions

玻璃钝芯片结

High temperature soldering guaranteed:

260°C/10 seconds at 5lbs., (2.3kg)tension

高温焊接保证：300°C/10 秒，拉力，2.3kg。

机械数据

MECHANICAL DATA

Terminals:Nickelplated.25 " (6.35mm) Faston lugs

端子：镀镍 0.25 " (6.35mm) 接线端子Mounting

position: Bolt doen on heat_sink with Silicone

thermal compound between bridge and Mounting

surface for maximum heat transfer efficiency. with

number 5 screw

安装位置：用 M5 螺丝固定在散热片上，桥和安

装表面之间填充硅热混合物以达到最佳的散热效

果

polarity: polarity symbols molded on body

极性：极性符号铸在管体上

Weight: 15 grams

重量：15 克

最大额定值 Absolute MAX rating

Item 项 目	Symbol 符号	Conditions 条 件	Ratings 额定值	Unit 单位
Storage temperature 贮存温度	Tstg		-40~150	°C
Operating junction Temperature 结 温	T _J		150	°C
Max reverse voltage 最大反向电压	V _{RM}			
KBPC1502 -W			200	V
KBPC1504 -W			400	V
KBPC1506 -W			600	V
KBPC1508 -W			800	V
KBPC1510 -W			1000	V
Average rectified forward current 平均正向整流电流	I _o	50Hz Sine wave resistance load T _c =85°C 50Hz 正弦波电阻负载	15	A
Peak Surge forward Current 浪涌电流	I _{FSM}	Non-repetitive 50Hz 10ms Sine wave T _j =25°C 不重复 50Hz 10ms 正弦波	400	A
Dielectric strength 绝缘强度	V _{dia}	Terminals to case AC 1 minute 端子与管壳间 AC 1 分钟	2	KV

电性特征

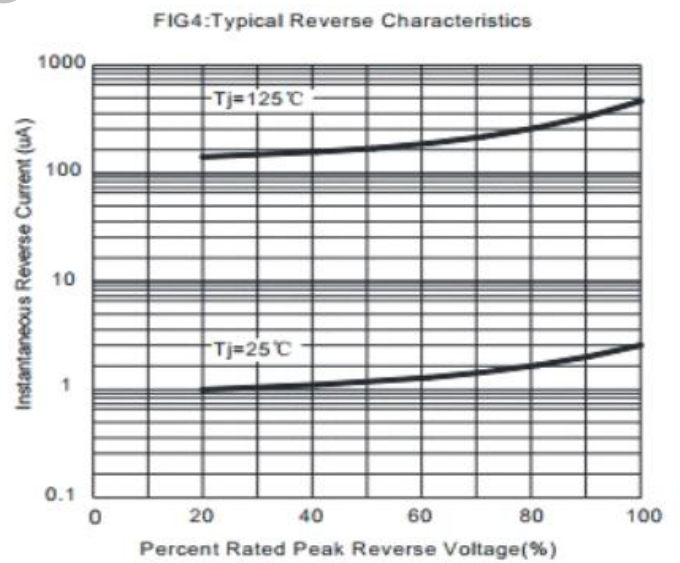
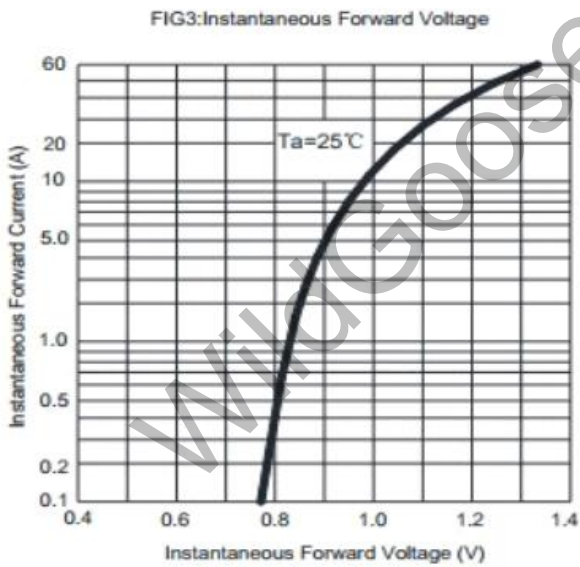
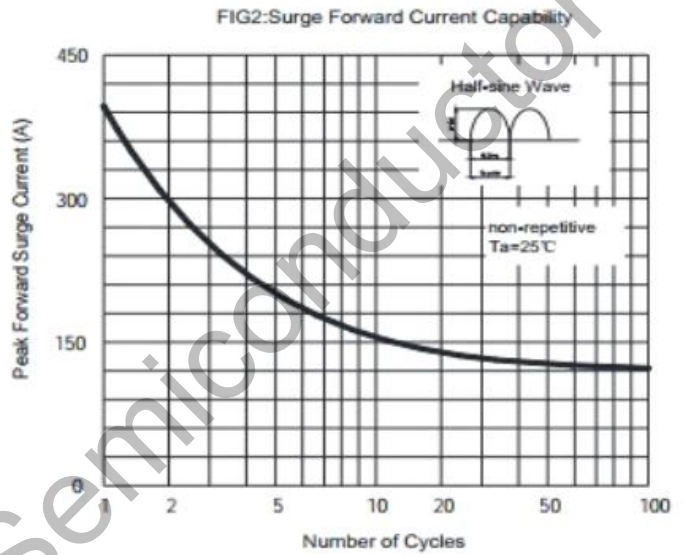
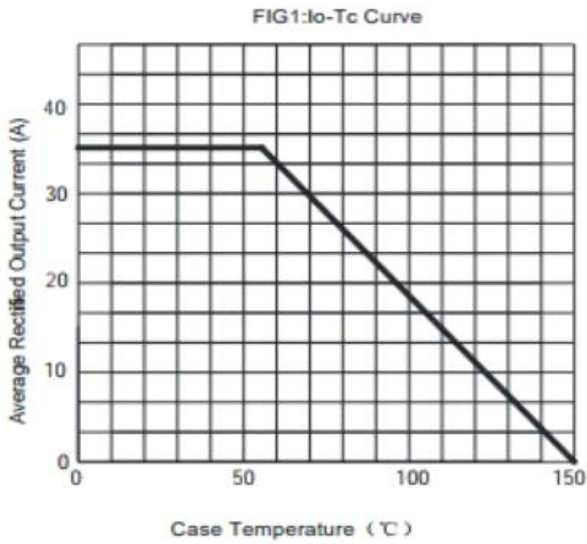
Electrical characteristics TA=25°C

Forward Voltage 正向电压	V _F	I _F =12.5A	Max 1.05	V	
Reverse current 反向漏电流	I _R	V _R =V _{RM}	Max 10	μA	
Thermal reslstance 热 阻	Q _{JC}	Junction to Case 结点管壳间	Max 1.5	°C/W	

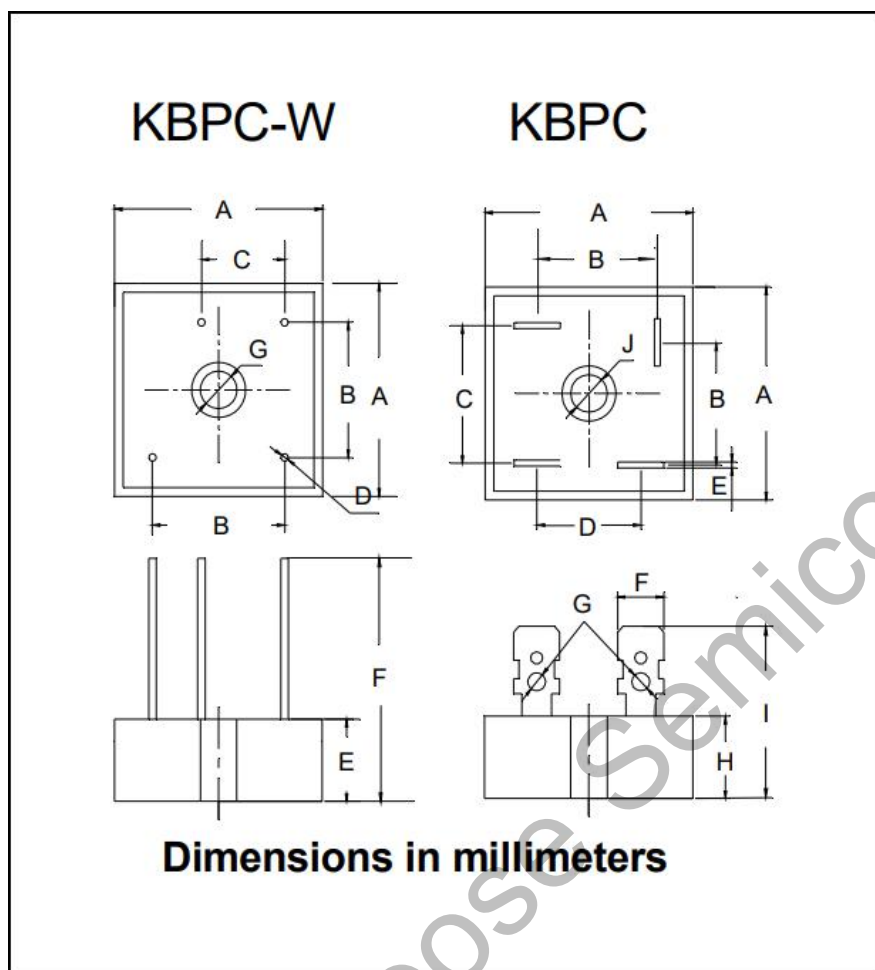
特性曲线

RATONG and characteristic

■ Characteristics (Typical)

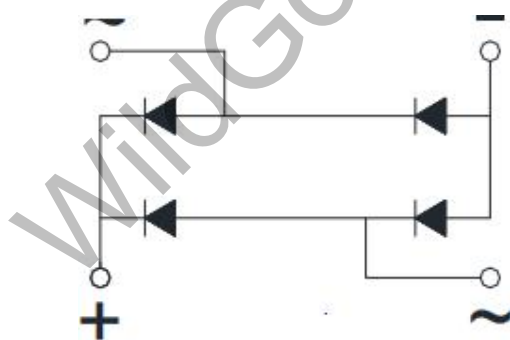


外型尺寸



KBPC-W		
Dim	Min	Max
A	28.2	28.8
B	17.1	19.1
C	10.4	12.4
D	0.95	1.05
E	10.8	11.2
F	30	
G	5	5.5

KBPC		
Dim	Min	Max
A	28.2	28.8
B	15.3	17.3
C	17.1	19.1
D	13.2	15.2
E	0.75	0.85
F	6.2	6.4
G	2.3	2.5
H	10.8	11.2
I	19	
J	5	5.5



主要原材料

序号	原材料	型号	规格	用量	产地	备注
1	芯片	140		4只	上海	
2	桥壳	铝壳	28X28	1只	上海	
3	环氧树脂	9001A/B	黑色	7Kg	江苏	